

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SAFI-TECH, INC.	06/27/2023
RECEIVING PARTY DATA	
Name:	THE INDIUM CORPORATION OF AMERICA
Street Address:	301 WOODS PARK DRIVE
City:	CLINTON
State/Country:	NEW YORK
Postal Code:	13323
PROPERTY NUMBERS Total: 13	
Property Type	Number
Patent Number:	11059098
Application Number:	17342339
Application Number:	17383150
PCT Number:	US2021043042
Application Number:	63264422
Application Number:	18065356
Application Number:	63371994
Patent Number:	11633702
Application Number:	18185788
PCT Number:	US2022035915
Application Number:	17564325
Application Number:	18193426
PCT Number:	US2021065451
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	8587208900
Email:	DOCKETING@SHEPPARDMULLIN.COM
Correspondent Name:	SHEPPARD, MULLIN, RICHTER & HAMPTON LLP
Address Line 1:	650 TOWN CENTER DRIVE, 4TH FLOOR

PATENT

Address Line 4:	COSTA MESA, CALIFORNIA 92626
ATTORNEY DOCKET NUMBER:	21XD-373825
NAME OF SUBMITTER:	JONATHAN A. MARINA
SIGNATURE:	/Jonathan A. Marina/
DATE SIGNED:	08/01/2023
Total Attachments: 4 source=Patent_Assignment-SAFI-Tech_to_Indium_Corporation_-_Final.docx(26599475.1)#page1.tif source=Patent_Assignment-SAFI-Tech_to_Indium_Corporation_-_Final.docx(26599475.1)#page2.tif source=Patent_Assignment-SAFI-Tech_to_Indium_Corporation_-_Final.docx(26599475.1)#page3.tif source=Patent_Assignment-SAFI-Tech_to_Indium_Corporation_-_Final.docx(26599475.1)#page4.tif	

PATENT ASSIGNMENT

THIS PATENT ASSIGNMENT (“Assignment”), effective as of June 27, 2023 (“**Effective Date**”), is made by **SAFI-TECH, INC.**, a Delaware corporation having a place of business at 1575 Food Sciences Building, 536 Farmhouse Lane, Ames, IA 50011-1061 (“**Assignor**”) to and for the benefit of **THE INDIUM CORPORATION OF AMERICA**, a New York corporation having a place of business at 301 Woods Park Drive, Clinton, New York 13323 (“**Assignee**”) with reference to the following facts:

WHEREAS, Assignor and Assignee have entered into that certain Asset Purchase Agreement dated June 7, 2023 (“**Purchase Agreement**”);

WHEREAS, pursuant to the Purchase Agreement, Assignor wishes to execute this Assignment with respect to the patents and patent applications identified on the attached Schedule A (collectively, the “**Patents**”);

NOW, THEREFORE, for good and valuable consideration as set forth in separate agreements between Assignor and Assignee, the receipt of which is hereby acknowledged, Assignor and Assignee agree as follows:

1. Assigned Assets. In accordance with the Purchase Agreement, Assignor hereby sells, transfers, conveys and assigns, and hereby sets over unto Assignee, its successors, assigns and legal representatives, and Assignee hereby accepts, all of Assignor’s right, title and interest, in and outside of the United States, in and to (a) all inventions disclosed in the Patents, including, without limitation, any continuation, divisional, reissue, reexamination, continuation-in-part, extension, post-grant review, foreign counterparts and foreign equivalents thereof; including the right to claim priority of the Patents, and the right to file any subsequent patent application claiming priority to any of the Patents (the “**Patent Rights**”) and (b) all enforcement rights under any of the Patent Rights described in this Section, including, without limitation, all of its causes of action and other enforcement rights for (i) damages, (ii) injunctive relief, (iii) any other remedies of any kind for past, current and future infringement, and (iv) rights to collect royalties or other payments under any of the Patent Rights (“**Additional Rights**”) (all of the foregoing items set forth in this **Section 1** being collectively referred to as the “**Assigned Assets**”).

2. Patent Office Authorization. Assignor hereby authorizes and requests the patent office of the country in which this Assignment is recorded to issue to Assignee or its successors or assigns, all patents within and issuing from the Assigned Assets.

3. Further Documentation. Assignor hereby agrees, upon request of Assignee, its successors, assigns or legal representatives, and without further remuneration, to execute any and all papers desired by and necessary for Assignee, its successors, assigns and legal representatives, for the filing, prosecution, granting and maintenance of the Assigned Assets and the perfecting of title thereto in Assignee, its successors, assigns and legal representatives.

4. Cooperation. Assignor furthermore agrees to execute any papers, provide any information and testify in any legal or administrative proceeding, interference or litigation at the request of Assignee, its successors, assigns and legal representatives, to the extent reasonably

necessary, for purposes of Assignee's, its successors', assigns' and legal representatives' full enjoyment, protection, enforcement and title in and to the Assigned Assets; provided, however, that Assignee shall reimburse Assignor for any reasonable, out-of-pocket travel expenses and daily loss in personal wages caused by any testifying required by this Section.

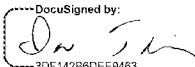
5. Power of Attorney. Assignor hereby irrevocably designates and appoints Assignee and its duly authorized officers and agents as Assignor's agents and attorneys-in-fact, which appointment is coupled with an interest, to: (i) act for and on Assignor's behalf to execute, verify and file any documents or instruments for Assignee's purposes of owning, controlling, defending, enforcing and perfecting the Assigned Assets or otherwise seeking intellectual property protection or registrations for the Assigned Assets; and (ii) do all other lawfully permitted acts to fully vest Assignee's ownership rights in the Assigned Assets, all with the same legal force and effect as if executed, filed or performed by Assignor.

6. Severability. In the event that, and only to the extent that: (i) any provision of this Assignment violates the applicable law of any country or jurisdiction in which this Assignment is recorded, registered or asserted for legal purposes; or (ii) any court of competent jurisdiction adjudges any provision of this Assignment to be invalid or unenforceable, such violation or judgment shall not affect, impair or otherwise invalidate the remainder of this Assignment in such country or jurisdiction, but shall be confined in its operation to the specific provision of this Assignment which gave rise to such violation or judgment.

IN WITNESS WHEREOF, the parties hereto have duly executed this Patent Assignment as of the Effective Date first set forth above.

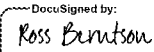
ASSIGNOR:

SAFI-TECH, INC.

Signature:  _____
Print Name: Dr. Ian Tevis
Title: President

ASSIGNEE:

THE INDIUM CORPORATION OF AMERICA

Signature:  _____
Print Name: Ross M. Berntson
Title: President

Schedule A**PATENTS**

Patent No./ Publication No./ Application No.	Title	Application Date / (Priority Date)	Issue Date
Patent No. US11059098 U.S. Application No. 15/932,990	Direct printing and writing using undercooled metallic core-shell particles	6-Jun-18	13-Jul-21
Pub. No. US20210291269A1 U.S. Application No. 17/342,339	Direct printing and writing using undercooled metallic core-shell particles	8-Jun-21	
Pub. No. US20220023940A1 US Application No. 17/383,150	Undercooled liquid metallic droplets having a protective shell	22-Jul-21	
PCT/US2021/043042 (published as WO2022020762A1, corresponds to 17/383,150)	Undercooled liquid metallic droplets having a protective shell	(24-Jul-20) (Priority Date)	
Chinese Application (corresponds to 17/383,150)	Undercooled liquid metallic droplets having a protective shell	16-Mar-23	
Japanese Application 2023- 505413 (corresponds to 17/383,150)	Undercooled liquid metallic droplets having a protective shell	24-Jan-23	
Malaysia Application PI2023000396 (corresponds to 17/383,150)	Undercooled liquid metallic droplets having a protective shell	24-Feb-23	
Korean Application KR1020237006695A (corresponds to 17/383,150)	Supercooled liquid metal droplet with protective shell	25-Jan-23	
US Application No. 63/264,422	SELF-ASSEMBLY WITH SUPERCOOLED LIQUID METAL MICROCAPSULES	(22-Nov-21) (Priority Date)	

Patent No./ Publication No./ Application No.	Title	Application Date / (Priority Date)	Issue Date
US Application No. 18/065,356	SOLDER MATERIALS INCLUDING SUPERCOOLED MICRO-CAPSULES AND ALLOYED PARTICLES	13-Dec-22	
US Application No. 63/371,994	METHODS AND APPARATUSES FOR SUPERCOOLED MICRO-CAPSULES	(19-Aug-22) (Priority Date)	
Patent No. US11633702B2 US Application No. 17/855,942	Solder paste on demand apparatus	1-Jul-22	25-Apr-23
U.S. Application No. 18/185,788 filed March 17, 2023 (continuation-in-part of US Application No. 17/855,942 that issued as US11633702)	Solder paste on demand apparatus	17-Mar-23	
PCT Application No. PCT/US2022/35915 (published as WO2023283122A1, corresponds to US Application No. 17/855,942)	Solder paste on demand apparatus	1-Jul-22	
Pub. No. US20220212250A1 US Application No. 17/564,325	System and method for manufacture of undercooled metallic core-shell particles	29-Dec-21	
U.S. Application No. 18/193,426 filed March 30, 2023 (continuation-in-part of US Application No. 17/564,325)	System and method for manufacture of undercooled metallic core-shell particles	30-Mar-23	
PCT/US2021/065451 (published as WO2022147079A1, corresponds to 17/564,325)	System and method for manufacture of undercooled metallic core-shell particles	29-Dec-21	

End of Schedule A